



Synamic6GX

(FR15.1) Halogen Free, Very Low Loss & High Reliability Material

FEATURES

- Low Dk/Df@10GHz: 3.73/0.005
- High heat resistance: T300 >60min
- Lower Z-axis CTE
- Lower moisture absorption
- MOT 150°C

APPLICATIONS

High Speed Network equipment,
Server, Switch, Storage and Routers,
High Performance Computing,
Optical Modulus, etc.

GENERAL PROPERTIES

Test Items	Test Method	Test Condition	Unit	Typical Value
Tg	IPC-TM-650 2.4.25D	DSC	°C	172
Td	IPC-TM-650 2.4.24.6	TGA (5% Wt. loss)	°C	405
T288	IPC-TM-650 2.4.24	TMA	min	>60
T300	IPC-TM-650 2.4.24	TMA	min	>60
Thermal Stress	IPC-TM-650 2.4.24.1	288°C, solder dipping	s	100
CTE	IPC-TM-650 2.4.24 (TMA)	Before Tg	ppm/°C	31
	IPC-TM-650 2.4.24 (TMA)	After Tg	ppm/°C	205
	IPC-TM-650 2.4.24 (TMA)	50~260°C	%	2.2
Dielectric Constant	IPC-TM-650 2.5.5.9 (1GHz)	C-24/23/50	-	3.87
	IPC-TM-650 2.5.5.5 (10GHz)	C-24/23/50	-	3.73
Dissipation Factor	IPC-TM-650 2.5.5.9 (1GHz)	C-24/23/50	-	0.0023
	IPC-TM-650 2.5.5.5 (10GHz)	C-24/23/50	-	0.0050
Peel Strength (RTF3/10z)	IPC-TM-650 2.4.8	After Thermal Stress 288°C/10s	N/mm	0.9
Water Absorption	IPC-TM-650 2.6.2.1	D-24/23	%	0.08
Flammability	UL 94	A	Rating	V-0

Remarks:

1. Meet IPC-4101/130 specification sheet.
2. All the typical value is based on the 0.76mm (6*2116) specimen, but not guarantee data.
3. All the typical values listed above are for your reference only and not intended for specification. Please contact Shengyi Technology Co., Ltd. for detailed information. All rights from this data sheet are reserved by Shengyi Technology Co., Ltd.

Explanation: C=Humidity conditioning, D=Immersion conditioning in distilled water, E=Temperature conditioning. The first digit following the letter indicates the duration of preconditioning in hours, the second digit the preconditioning temperature in °C and the third digit the relative humidity.